

10/009822

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PATENT NUMBER and  
ISSUE DATE

## U.S. UTILITY Patent Application

APPL NUM 10009822	FILING DATE 12/13/2001	CLASS 361	SUBCLASS 2835	GAU <i>KOehler</i>	EXAMINER LA VILLA
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*10/009822-2+*

**\*\*CONTINUING DATA VERIFIED:**  
THIS APPLICATION IS A 371 OF PCT/JP01/03164 04/12/2001

*M.L.*

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**\*\* FOREIGN APPLICATIONS VERIFIED:**

JAPAN 17584/2000 01/26/2000

JAPAN 113006/2000 04/14/2000 *two 96*JAPAN 372405/2000 12/07/2000 *m*

PG-PUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	
Foreign priority claimed	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO
35 USC 119 conditions met	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no		Q67726
Verified and Acknowledged Examiner's initials <i>M.L.</i>			
TITLE : Material of heat-dissipating plate on which semiconductor is mounted, method for fabricating the same, and ceramic package produced by using the same			
U.S.DEP.T. OF COMM./PAT.& TM-PTO-436L (Rev. 12-94)			

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Assistant Examiner <i>Michael LaVilla</i>	Total Claims 6 / Print Claim for O.G. 1
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drawn 3	Fig.s Drawn 7
		Print Fig. 4	
TERMINAL DISCLAIMER		Primary Examiner Application Examiner	
PREPARED FOR ISSUE			
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